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CONFIRMATION NO. 1718

<b>SERIAL NUMBER</b> 10/580,361	<b>FILING or 371(c) DATE</b> 04/18/2007 <b>RULE</b>	<b>CLASS</b> 257	<b>GROUP ART UNIT</b> 2812	<b>ATTORNEY DOCKET NO.</b> LEO 003 PA		
<b>APPLICANTS</b> Roy Knechtel, Geraberg, GERMANY; / SBG/ Andrej Lenz, Tittmoning, GERMANY;						
<b>** CONTINUING DATA *****</b> This application is a 371 of PCT/DE04/02638 11/29/2004 / SBG/						
<b>** FOREIGN APPLICATIONS *****</b> GERMANY 103 55 728.8 11/28/2003 / SBG/						
<b>** IF REQUIRED, FOREIGN FILING LICENSE GRANTED **</b> 10/31/2007						
Foreign Priority claimed <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No 35 USC 119(a-d) conditions met <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No Verified and Acknowledged <u>/SCOTT B GEYER/</u> Examiner's Signature		<input type="checkbox"/> Met after Allowance Initials	<b>STATE OR COUNTRY</b> GERMANY	<b>SHEETS DRAWINGS</b> 1	<b>TOTAL CLAIMS</b> 28	<b>INDEPENDENT CLAIMS</b> 4
<b>ADDRESS</b> STEVENS & SHOWALTER LLP 7019 CORPORATE WAY DAYTON, OH 45459-4238 UNITED STATES						
<b>TITLE</b> Production Of Semiconductor Substrates With Buried Layers By Joining (Bonding) Semiconductor Wafers						
<b>FILING FEE RECEIVED</b> 1630	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:		<input type="checkbox"/> All Fees			
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